

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A system (10) for positioning components (20) of different thicknesses on a component platform (35), comprising:
 - a frame (15);
 - a tool head (25) connected to the frame (15), the tool head (25) being vertically movable;
 - a retractable vacuum tube (26) receivable within the tool head (25); and
 - a grasping assembly (60) which can be actuated to securely hold the vacuum tube (26) in a fixed position relative to the tool head (25) after the vacuum tube (26) has been at least partially received within the tool head (25), and wherein the distance the vacuum tube (26) retracts into the tool head (25) depends upon the thickness of the component (20).
2. (Previously Presented) The system of Claim 1, wherein the grasping assembly (60) comprises a bushing (61) which is movable along a collet (62).
3. (Previously Presented) The system of Claim 1, wherein the grasping assembly (60) further comprises a knob (63) for manually rotating the vacuum tube (26) about an axis extending longitudinally therethrough.
4. (Previously Presented) The system of Claim 1, wherein the frame (15) supports the tool head (25) such that the tool head (25) can be moved in X and Y directions.
5. (Previously Presented) The system of Claim 1, wherein the components (20) comprise electronic components.
6. (Previously Presented) The system of Claim 5, wherein the electronic components (20) comprise integrated circuit chips.

7. (Previously Presented) The system of Claim 1, wherein the component platform (35) comprises a printed circuit board.

8. (Withdrawn) A method of positioning a component on a target surface, comprising:

positioning a tool head over the component, the tool head having a retractable vacuum tube extending downwardly therefrom;

lowering the tool head until the vacuum tube contacts an upper surface of the component and is pushed into a retracted position within the tool head;

securely holding the vacuum tube in a fixed position relative to the tool head after the vacuum tube has been pushed into the retracted position within the tool head;

lifting the tool head, thereby lifting the component with the vacuum tube;

positioning the tool head over the target surface;

lowering the tool head such that a bottom surface of the component is positioned in contact with the target surface; and

releasing the component from the vacuum tube.

9. (Withdrawn) The method of Claim 8, wherein the vacuum tube is securely held in a fixed position relative to the tool head after the vacuum tube has been pushed into the retracted position within the tool head by:

moving a bushing along a collet within the tool head.

10. (Withdrawn) The method of Claim 8, wherein the component comprises an electronic component.

11. (Withdrawn) The method of Claim 10, wherein the electronic component comprises an integrated circuit chip.

12. (Withdrawn) The method of Claim 8, wherein the target surface comprises a printed circuit board.

13. (Withdrawn) The method of Claim 12, further comprising:
placing the printed circuit board on a movable component platform; and
positioning the printed circuit board by moving the component platform.

14. (Withdrawn) The method of Claim 13, wherein the component platform and
the tool head are both attached to a frame of a positioning system, and wherein each of the
component platform and the tool head are separately positionable in X and Y directions.